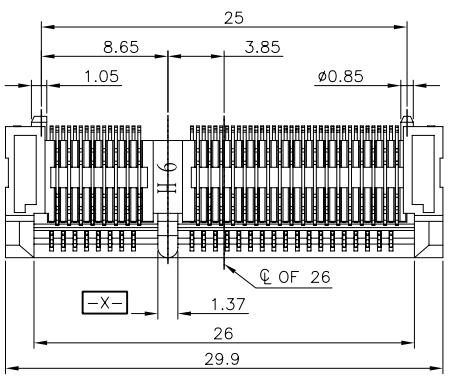
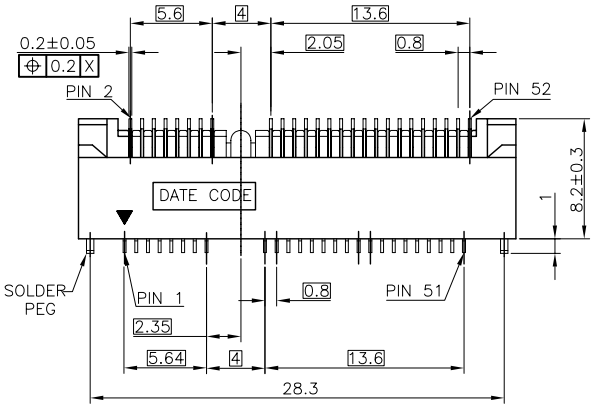
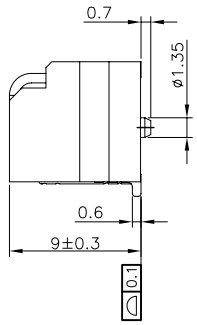
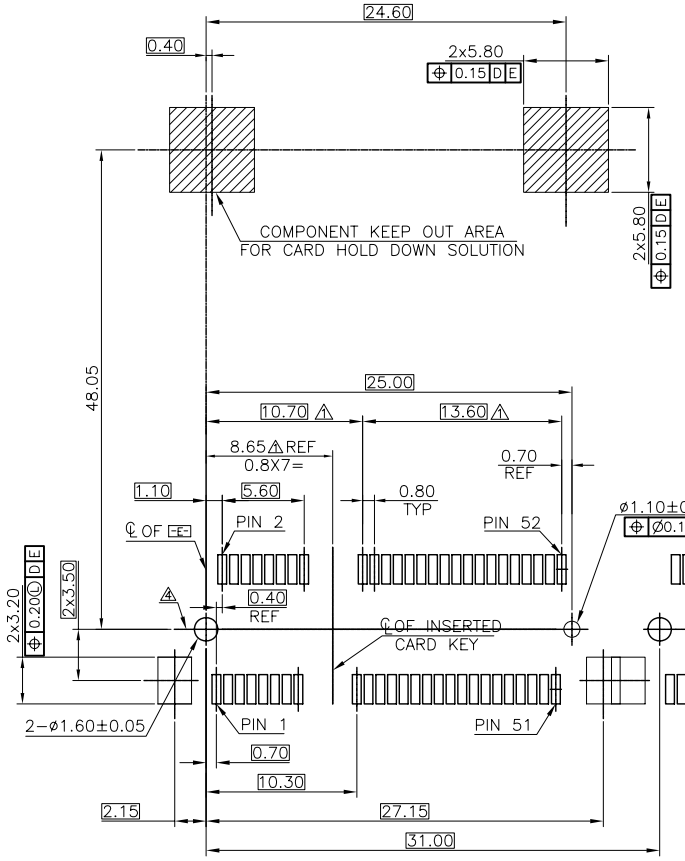
REV.	DESCRIPTION	DATE	DWN	APVD
1	PRELIMINARY	27APR09	JC	BC

Plating: : GOLD FLASH 1μ" OVER Ni 50 μ"









RECOMMENDED P.C.BOARD PATTERN LAYOUT
(SIDE BY SIDE)

MATERIAL
▲THIS PART DON'T CONTAIN ANY SUBSTANCES WHICH ARE SPECIFIED IN SS-00259
HOUSING : THERMO PLASTIC UL94V-0
CONTACT : COPPER ALLOY
SOLDER PEG :COPPER ALLOY

SPECIFICATION
CURRENT RATING : 0.5A 50V AC/DC
CONTACT RESISTANCE : 55 mΩ
INSULATION RESISTANCE : 500 MΩ
OPERATING TEMPERATURE : -25°C~80°C

GOLD FLASH	J27-0007-01
MIN. GOLD THICKNESS	PART NUMBER

TOLERANCES UNLESS OTHERWISE SPECIFIED:
0 PLC ± -
1 PLC ± 0.3
2 PLC ± 0.2
3 PLC ± -
4 PLC ± -
ANGLES ± 3°

MATERIAL: SEE NOTE
FINISH: SEE NOTE
PROJECTION

DWN: JOHN_CHANG 27APR2009
CHK: MARKS_CHEN 27APR2009
APVD: BEST_CHANG 27APR2009
PRODUCT SPEC
APPLICATION SPEC
WEIGHT: - GRAMS
DIMENSIONS: MM

HAOGUO XING YE SHARE CO.,LTD.

NAME: 0.80MM PITCH MINI PCI EXPRESS H=9.0mm CONNECTOR CUSTOMER DRAWING

SIZE	DRAWING NO	RESTRICTED TO
A3	J27-0007	-

CUSTOMER DRAWING | SCALE - | SHEET 1 OF 1 | REV 1